

SEMICON[®]
Europa2010



PROGRAMS & EVENTS SPONSORSHIP OPPORTUNITIES



2010

EU

the elements of innovation



19-21 OCTOBER

Messe Dresden, Dresden Germany

www.semiconeuropa.org





41 programs and events – SEMICON Europa is your platform to exchange and drive forward technology advancements

12 Technology conferences


13 Free technology and standardization session

4 Executive and networking events

12 Courses

Key Segments discussed at SEMICON Europa

- Semiconductor front-end and back-end
- MEMS Micro-Electro-Mechanical Systems
- Plastic Electronics

	Exhibition	TechARENA	Conference		Exec. Programs	Standards
	Halls 1, 2, 4	Free Entrance for Visitors	Semiconductors	MEMS, Test & Packaging	Business & Market	Free Participation
Monday October 18			14 th Fab Managers Forum Networking Evening	International MEMS/MST Industry Forum		 SEMI [®] International Standards
Tuesday October 19	Exhibition 10:00 – 17:00 Show Floor Highlights: - Science Park - Secondary Equipment, Services and Technology Pavilion - MEMS, Test and Packaging Pavilion	SEMI Standards How does it work? EU funded R&D projects Current Activities Automation and Software Exhibitor Presentations MEMS / MST Exhibitor Presentations	14th Fab Managers Forum - Cost-efficient Fab-Services - Fab Automation and Control - Introduction of Advanced Technologies	International MEMS/MST Industry Forum Advanced Packaging Manufacturing Conference	EXPO Opening Ceremony Press Conference EU funded R&D projects ← TechARENA 4rd Executive Summit and Reception	SEMI Standards How does it work? ← TechARENA Committee - & Task Force Meetings Silicon Wafer
Wednesday October 20	Exhibition 10:00 – 17:00 Show Floor Highlights: - Science Park - Secondary Equipment, Services and Technology Pavilion - MEMS, Test and Packaging Pavilion	Lithography Session Key note Speeches Exhibitor Presentations Test Exhibitor Presentations IC Industry Awards - by EuroAsia Packaging - Exhibitor Presentations Metrology Session Key note Speeches Exhibitor Presentations	Lithography Session ← TechARENA 450mm Session Progress Review (Organized by Fraunhofer IZB) Metrology Session ← TechARENA	Advanced Packaging Manufacturing Conference 12th European Manufacturing Test Conference (EMTC)	2nd European Cluster Breakfast IC Industry Awards - by EuroAsia ← TechARENA	Compound Semiconductor Materials Equipment Automation
Thursday October 21	Exhibition 10:00 – 16:00 Show Floor Highlights: - Science Park - Secondary Equipment, Services and Technology Pavilion - MEMS, Test and Packaging Pavilion	New Materials Session Key note Speeches Exhibitor Presentations Secondary Equipment, Services and Technology Key note Speeches Exhibitor Presentations	New Materials Session ← TechARENA	12th European Manufacturing Test Conference (EMTC) CAST Workshop	SEMI Members & Exhibitors Breakfast Market Briefing	Gases & Liquid Chemicals EHS

Plastic Electronics Conference and Exhibition
organized by Plastic Electronics Foundation | www.plastic-electronics-europe.com

CEI-Europe Courses in Advanced Technology
Courses organized by CEI | www.cei.se | www.semicon.europa.org/courses



Segments

Semiconductor

- Front-End
 - New Materials
 - Automation and Process Control
 - Metrology
 - Lithography
 - Refurbished Equipment
 - 14th Fab Managers Forum
 - 450mm session
- Back-End
 - 12th European Manufacturing Test Conference (EMTC)
 - CAST (Collaborative Alliance for Semiconductor Test) Dock & Mounting Workshop
 - Advanced Packaging Conference

MEMS

- International MEMS/MST Industry Forum

Plastic Electronics



SEMICON Europa is your platform to exchange and drive forward technology advancements

Free to all SEMICON Europa visitors

- Presentations on the showfloor TechARENA
 - TechARENA Lithography session (free)
 - TechARENA MEMS exhibitor presentations (free)
 - TechARENA Test exhibitor presentations (free)
 - TechARENA Packaging exhibitor presentations (free)
 - TechARENA R&D exhibitor presentations (free)
 - TechARENA Metrology exhibitor presentations (free)
 - TechARENA New Materials session (free)
 - TechARENA Automation and Process Control session (free)
- Standards Meeting
 - Compound Materials related Meetings (free)
 - Silicon Wafer related Meetings (free)
 - Gases and Liquid Chemicals related Meetings (free)
 - Equipment Automation related Meetings (free)
 - Environment, Health and Safety related Meetings (free)



From Executive Networking to Continuous Engineer Education

- Business and Networking
 - Market Briefing
 - 4th Executive Summit and Award Presentation
 - SEMI Members & Exhibitors Breakfast
 - 2nd Cluster Breakfast (organized by Silicon Saxony)
- CEI courses - Continuation Education Institute Europe
 - CMOS/BICMOS Process Integration and Engineering
 - Silicon Device Technology: Materials and Processing Overview
 - Advanced Lithography Technologies – Fundamentals and Applications
 - Micro Fabrication Technology. For MEMS and NEMS
 - Plasma-Assisted Etching and Reactive Ion Etching. Using High And Low Density Plasmas
 - Plasma Etching for CMOS Technology and ULSI Applications
 - Chip Interconnection Technology And Process Integration
 - Copper Low-k Interconnect Technology. Processing and Reliability of Cu Low-k Interconnect Metallization
 - Megafunction Electronics and Photonics Based on 3D Integration. Applications for 3D Si-Based ICs, Flexible Polymer Electronics, Thin Film Solar Cells, and OLEDs
 - Advanced Photovoltaics and Electronics. Device Reliability and Lifetime Performance Applications for Thin Film Electronics and Photovoltaics
 - Yield and Reliability in VLSI Development and Manufacturing
 - IC Debug and Fault Isolation



Top level industry keynotes

- **Keynote: “Trends for Automotive Micromechanical Sensors”**
Jiri Marek, Senior Vice President Engineering Sensors
Bosch
- **Keynote “Monolithic to Multi Chip: Smart Partitioning Adds Customer Value”**
Rob O'Reilly, Senior Technical Staff, MEMS Sensor and Technology Group
Analog Devices
- **Keynote “III-V and III-V on Si for future nanoelectronics”**
Robert Chau, Intel Senior Fellow and Director, Technology and Manufacturing Group
Intel
- **Keynote: “System Design, Drives Package Design, Drives Silicon Design”**
Peter Robinson, Package Design and Development Director
CSR
- **Keynote: “Revolution and Evolution of Consumer MEMS Applications”**
Leopold Beer, Director Marketing
Bosch Sensortec
- **Keynote: “High Brightness Phosphor Converted White LEDs – Challenges and Solutions”**
Raimund Schwarz, Senior Director
Osram Opto Semiconductors



Top ranking companies chose to present at SEMICON Europa

**Companies that have confirmed their participation in
the SEMICON Europa 2010 conferences include:**

- Altis
- Bosch
- CSR (Cambridge Silicon Radio)
- GLOBALFOUNDRIES
- Intel
- Lfoundry
- Nanium
- Numonyx
- Osram
- Texas Instruments
- X-Fab
- Analog Devices
- Colibrys
- Freescale
- Infineon
- IBM
- Micron
- Nokia
- NXP
- STMicroelectronics
- Thales



PROGRAMS & EVENTS

SPONSORSHIP OPPORTUNITIES





PROGRAMS & EVENTS

SPONSORSHIP OPPORTUNITIES

SEMICON Europa 2010 offers a wide range of program sponsorship possibilities with many benefits for you and your company. The sponsorship opportunities are divided in different categories and scales. Please consult the details on the following pages, and **benefit up to 40% discount!**

- Confirmed exhibitors get a 10% discount on all sponsorship packages
- SEMI Members get an additional 10% discount on all sponsorship packages
- Sponsorships confirmed before 30 June 2010 – an additional 20% discount!





TECHNICAL PROGRAMS SPONSORSHIP

12th European Manufacturing Test Conference (EMTC)

& CAST Workshop on Dock & Mounting

(20-21 Oct 2010)

Sponsorship package includes:

Prior to the event benefits

- Logo on the program website
- Includes one article/advertorial in EuroAsia magazine
- Link to video / related press release on the SEMICON Europa website
- **5** complementary conference entrance tickets for company employees
- **30** complementary conference entrance tickets to invite customers

During the event benefits

- Logo on the programs display in the entrance area of the exhibition
- Opportunity to distribute company brochures
- Banner in the conference room (free standing only, self-delivery) + possibility to bring table-top
- Logo on welcome screen/slide/video during the conference
- Promotion of company as lunch and reception sponsor
- Promotion on all printed material (event flyer, show catalogue, program folder)
- Price: 9500 EUR
- Maximum two sponsorships available **(1 SOLD)**

AGENDA LINK: <http://www.tinyurl.com/SE10-EMTC>

Organizing Committee



Stefan Gasteiger, Advantest



Klaus-Detlef Paesch, GlobalFoundries



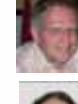
Michael Goldbach, LTX



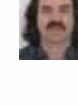
Roger Barth, Numonyx



Chris Portelli-Hale, STMicroelectronics



Davide Appello, STMicroelectronics



Martin Stadler, Teradyne



Ulrich Schoettmer, Verigy



René Segers



Stefan Eichenberger, NXP



TECHNICAL PROGRAMS SPONSORSHIP

Advanced Packaging Manufacturing Conference & R&D Workshop

(19-20 Oct 2010)

Sponsorship package includes:

Prior to the event benefits

- Logo on the program website
- Includes one article/advertorial in EuroAsia magazine
- Link to video / related press release on the SEMICON Europa website
- **5** complementary conference entrance tickets for company employees
- **30** complementary conference entrance tickets to invite customers

During the event benefits

- Logo on the programs display in the entrance area of the exhibition
- Opportunity to distribute company brochures
- Banner in the conference room (free standing only, self-delivery) + possibility to bring table-top
- Logo on welcome screen/slide/video during the conference
- Promotion of company as lunch and reception sponsor
- Promotion on all printed material (event flyer, show catalogue, program folder)
- Price: 9500 EUR
- Maximum two sponsorships available (**1 SOLD**)



AGENDA LINK: <http://www.tinyurl.com/SE10-PACK>

Organizing Committee



Andy Longford, PandA Europe



Andreas Fischer, Bosch



Ignas van Dommelen, Elmos



Philip Homami, F+K Delvotec



Rolf Aschenbrenner, Fraunhofer IZM



Jens Mueller, IMAPS Europe Chapter



Eric Beyne, IMEC



Klaus Pressel, Infineon



Eef Bagerman, NXP



Andreas Dill, Oerlikon



Thomas Oppert, PAC TECH



Mark Shaw, STMicroelectronics



Steffen Kroehnert, Nanium



Graham Jones, Henkel



TECHNICAL PROGRAMS SPONSORSHIP

International MEMS/MST Industry Forum

(18-19 Oct 2010)

Sponsorship package includes:

Prior to the event benefits

- Logo on the program website
- Includes one article/advertorial in EuroAsia magazine
- Link to video / related press release on the SEMICON Europa website
- **5** complementary conference entrance tickets for company employees
- **30** complementary conference entrance tickets to invite customers

During the event benefits

- Logo on the programs display in the entrance area of the exhibition
- Opportunity to distribute company brochures
- Banner in the conference room (free standing only, self-delivery) + possibility to bring table-top
- Logo on welcome screen/slide/video during the conference
- Promotion of company as lunch and reception sponsor
- Promotion on all printed material (event flyer, show catalogue, program folder)
- Price: 9500 EUR
- Maximum two sponsorships available (**1 SOLD**)



Organizing Committee



Gerhard Lammel, Bosch



Felix Rudolf, Colibrys



Peter Willemse, ASML



Erik Jung, Fraunhofer IMZ



Jérémie Bouchaud, iSuppli



Mikko Montonen, Okmetic



Christian Schaefer, PVA Tepla



Markus Gabriel, Suss MicroTec



Uwe Behringer, UBC Microelectronics



Uwe Schwarz, X-Fab



Jean-Christophe Eloy, Yole Développement



Paul Lindner, EVG



TECHNICAL PROGRAMS SPONSORSHIP

14th Fab Managers Forum (FMF)

(18-19 Oct 2010)

Sponsorship package includes:

Prior to the event benefits

- Logo on the program website
- Includes one article/advertorial in EuroAsia magazine
- **5** complementary conference entrance tickets for company employees
- **30** complementary conference entrance tickets to invite customers

During the event benefits

- Logo on the programs display in the entrance area of the exhibition
- Opportunity to distribute company brochures
- Banner in the conference room (free standing only, self-delivery) + possibility to bring table-top
- Logo on welcome screen/slide/video during the conference
- Promotion of company as lunch and reception sponsor
- Promotion on all printed material (event flyer, show catalogue, program folder)
- Price: 11500 EUR
- Maximum two sponsorships available **SOLD**

AGENDA LINK: <http://www.tinyurl.com/SE10-FMF>

2010 confirmed speakers:

- ABB, Detlef Nagel
- ALTIS, Francis Taroni
- BOSCH, Thorsten Widmer
- FREESCALE, Leslie Fowler
- GLOBALFOUNDRIES, Udo Nothelfer
- INFINEON Thomas Leitermann
- INFINEON, Wolfgang Scholl
- Lfoundry Günther Ernst
- MICRON, Riccardo Martorelli
- NIKON, Stuart Pinkney
- NUMONYX, Giorgio de Santi
- NXP, Volker Kuckhermann
- STMicroelectronics, Philippe Campion
- Texas Instruments Peter Schäffler
- TOKYO ELECTRON, David Brough
- X-FAB Mario von Podewils



TECHNICAL PROGRAMS SPONSORSHIP

450mm Session

(20 Oct 2010)

Sponsorship package includes:

- Opportunity to distribute company brochures
- Banner in the conference room (free standing only, self-delivery)
- Logo on the program website
- Logo on welcome screen/slide during the conference
- Logo on the programs display in the entrance area of the exhibition
- **2 complementary conference entrance tickets for company employees** (please send name and contact details)
- **3 complementary conference entrance tickets to invite customers** (please send name and contact details)

- Price: 2500 EUR
- Max. four sponsorship available





EXECUTIVE PROGRAMS SPONSORSHIPS

4th Executive Summit and International Reception (19 Oct 2010)

Sponsorship package includes:

- Opportunity to distribute company brochures
- Banner in the reception area (free standing only, self-delivery)
- Logo on the program website
- Logo on welcome screen/slide during the conference
- Logo on the programs display in the entrance area of the exhibition
- **10** complementary reception tickets for company employees (please send name and contact details)
- Price: 5500 EUR
- Max. three sponsorship available (**1 SOLD**)



Market Briefing (21 Oct 2010)

Sponsorship package includes:

- Opportunity to distribute company brochures
- Banner in the conference room (free standing only, self-delivery)
- Logo on the program website
- Logo on welcome screen/slide during the conference
- Logo on the programs display in the entrance area of the exhibition
- **2 complementary conference entrance tickets for company employees** (please send name and contact details)
- **3 complementary conference entrance tickets to invite customers** (please send name and contact details)
- Price: 2500 EUR
- Max. four sponsorship available





SEMI TECHNOLOGY ARENA SPONSORSHIPS

SEMI TechARENA – Branding (Show floor, 19-21 Oct 2010)

Sponsorship package includes:

- Opportunity to distribute company brochures
 - Logo on back and side wall
 - Logo on break slides
 - Logo on all printed advertising materials
 - Free standing banner on the TechARENA (free standing only, self-delivery)
 - Logo on the program website
 - Logo on welcome screen/slide during the presentations
 - Logo on the programs display in the entrance area of the exhibition
 - Company brochures on all seats
 - Two free speaking slots (10 min)
- Price: 9500 EUR
 - Max. two sponsorship available **SOLD**



<http://www.semiconeuropa.org/ProgramsandEvents/SEMITechArena>

SEMI TechARENA – Lunch Sponsor (Show floor, 19-21 Oct 2010)

Sponsorship package includes:

- Mentioning of the company name as lunch sponsor on one particular day
 - Free standing banner on the TechARENA (free standing only, self-delivery)
- Day 1: New Materials I
Automation, Software and Process Control
MEMS/MST Exhibitor Presentations
-
- Day 2: New Materials II
Metrology Session
Test, Packaging and Metrology Exh. Presentations
-
- Day 3: Lithography
SOLD Secondary Equipment



- Price: 2500 EUR per lunch
- Max. one sponsorship available for each day





MARKETING AND PROMOTION OPPORTUNITIES

CONFERENCE PENS

Sponsorship package includes:

- Distributed to all conference attendees and technology arena attendees
 - Exclusive for 1 company only
 - Quantity: max. 1000
 - Pens have to be self-delivered
-
- Price: 4500 EUR



CONFERENCE NOTEPADS

Sponsorship package includes:

- Distributed to all conference attendees and technology arena attendees
 - Exclusive for 1 company only
 - Quantity: max. 1000
 - Notepads have to be self-delivered
-
- Price: 4500 EUR





PROGRAMS PROMOTION TIMELINE

- January – Technical committee kick-off meetings to prepare conferences
- February – Call for Papers / mark-your-calendar email
- May – Keynotes confirmed and announced
- June – Agendas published
 - ❖ Special promotion activity to past attendees/recommended attendees
 - ❖ Special promotion via technical committees
 - ❖ Special promotion via sponsors
- September – Programs promotional campaign
- SEMI leverages its website, newsletters, printed promotional material, and advertisements in over 20 publications.



CONFIRM YOUR SPONSORSHIP

- Don't miss to confirm before 30 June 2010 to benefit up to 40% discount!
- Fax the completed 'Sponsorship Application' form
- Email your company logo (eps high-resolution format) to bmueLLer@semi.org
- Contact Beat Mueller to discuss how to enhance your participation at SEMICON Europa 2010
Beat Mueller, Director Member Relations, SEMI Europe
Email: bmueLLer@semi.org
Tel: +41 79 4656588